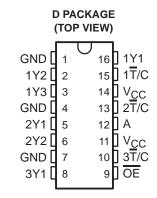
## CDC392 1-LINE TO 6-LINE CLOCK DRIVER WITH SELECTABLE POLARITY AND 3-STATE OUTPUTS

SCAS335A - DECEMBER 1992 - REVISED NOVEMBER 1995

- Low Output Skew for Clock-Distribution and Clock-Generation Applications
- TTL-Compatible Inputs and CMOS-Compatible Outputs
- Distributes One Clock Input to Six Clock Outputs
- Polarity Control Selects True or Complementary Outputs
- Distributed V<sub>CC</sub> and GND Pins Reduce Switching Noise
- High-Drive Outputs (-32-mA I<sub>OH</sub>, 32-mA I<sub>OL</sub>)
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Packaged In Plastic Small-Outline Package



### description

The CDC392 contains a clock-driver circuit that distributes one input signal to six outputs with minimum skew for clock distribution. Through the use of the polarity-control  $\overline{(T/C)}$  inputs, various combinations of true and complementary outputs can be obtained. The output-enable  $\overline{(OE)}$  input is provided to disable the outputs to a high-impedance state.

The CDC392 is characterized for operation from -40°C to 85°C.

**FUNCTION TABLE** 

	INPUTS	OUTPUT	
OE	T/C	Α	Y
Н	Х	Χ	Z
L	L	L	L
L	L	Н	Н
L	Н	L	Н
L	Н	Н	L

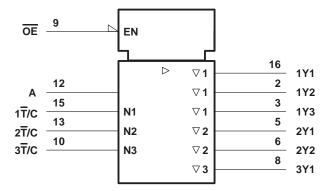


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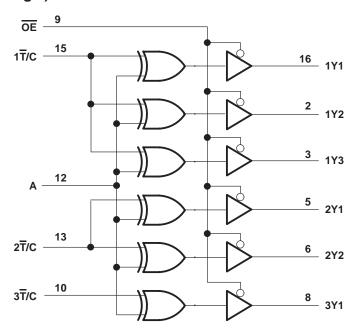


# logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

# logic diagram (positive logic)





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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

ply voltage range, $V_{CC}$ t voltage range, $V_{I}$ (see Note 1)	0.5 V to 7 V to V <sub>CC</sub> + 0.5 V 64 mA 18 mA 50 mA
age temperature range, T <sub>stg</sub>	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

### recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.75	5	5.25	V
VIH	High-level input voltage	2			V
V <sub>IL</sub>	Low-level input voltage			0.8	V
VI	Input voltage	0		VCC	V
loh	High-level output current			-32	mA
l <sub>OL</sub>	Low-level output current			32	mA
Δt/Δν	Input transition rise or fall rate			5	ns/V
f <sub>clock</sub>	Input clock frequency			90	MHz
TA	Operating free-air temperature	-40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

<sup>2.</sup> The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 300 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP <sup>†</sup>	MAX	UNIT
VIK	$V_{CC} = 4.75 \text{ V},$	$I_{I} = -18 \text{ mA}$	I <sub>I</sub> = -18 mA			-1.2	V
Voн	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -32 \text{ mA}$		3.85			V
V <sub>OL</sub>	$V_{CC} = 4.75 \text{ V},$	I <sub>OL</sub> = 32 mA				0.55	V
lį	$V_{CC} = 5.25 \text{ V},$	$V_I = V_{CC}$ or GND				±1	μΑ
loz	V <sub>CC</sub> = 5.25 V,	$V_O = V_{CC}$ or GND				±50	μΑ
	V <sub>CC</sub> = 5.25 V, V <sub>I</sub> = V <sub>CC</sub> or GND		Outputs high			10	
l <sub>CC</sub>		$I_{O}=0,$	Outputs low			40	mA
	AL = ACC OLGIND		Outputs disabled			10	
C <sub>i</sub>	V <sub>I</sub> = 2.5 V or 0.5 V				3		pF
Co	$V_O = V_{CC}$ or GND				7		pF

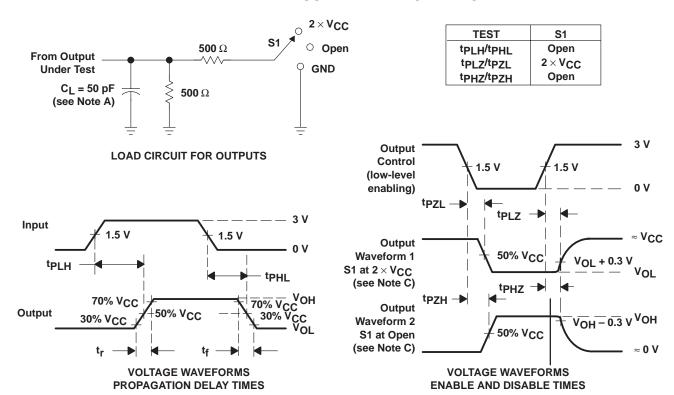
<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ 

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	TYP MA	X UNIT
<sup>t</sup> PLH	A	A Any Y	2	6	5 ns
<sup>t</sup> PHL	K	Ally I	1.5		5
<sup>t</sup> PLH	T/C	Any Y	1.5		5 ns
t <sub>PHL</sub>	1/C	Ally I	1.5		5
<sup>t</sup> PZH	ŌĒ	Any Y	1.5		6 ns
t <sub>PZL</sub>	OE	Ally I	3		8
<sup>t</sup> PHZ	<u> </u>	OE Any Y	1.5		5 ns
t <sub>PLZ</sub>	OE	Ally I	1.5		5
*	A	Any Y (same phase)		0	6
<sup>t</sup> sk(o)	A	Any Y (any phase)		2	2 ns
t <sub>r</sub>				1.4	ns
t <sub>f</sub>				0.83	ns



### PARAMETER MEASUREMENT INFORMATION

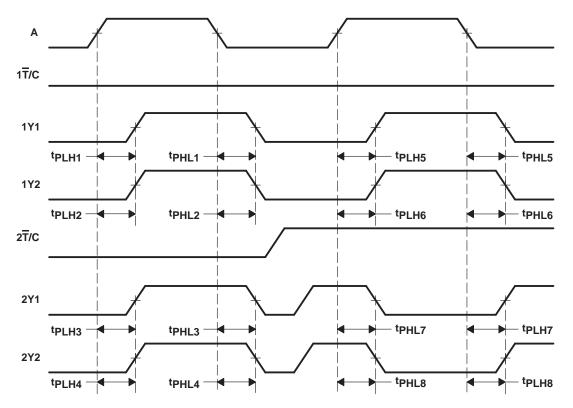


NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f \leq 2.5 \ ns$ ,  $t_f \leq 2.5 \ ns$ .
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

### PARAMETER MEASUREMENT INFORMATION



- NOTES: A. Output skew,  $t_{SK(0)}$ , from A to any Y (same phase), can be measured only between outputs for which the respective polarity-control inputs  $(\overline{T}/C)$  are at the same logic level. It is calculated as the greater of:
  - The difference between the fastest and slowest of tp<sub>L</sub>H from A↑ to any Y (e.g., tp<sub>L</sub>H<sub>n</sub>, n = 1 to 4; or tp<sub>L</sub>H<sub>n</sub>, n = 5 to 6)
  - The difference between the fastest and slowest of tPHL from A↓ to any Y (e.g., tPHLn, n = 1 to 4; or tPHLn, n = 5 to 6)
  - The difference between the fastest and slowest of tp<sub>LH</sub> from A↓ to any Y (e.g., tp<sub>LHn</sub>, n = 7 to 8)
  - The difference between the fastest and slowest of tp<sub>HL</sub> from A↑ to any Y (e.g., tp<sub>HLn</sub>, n = 7 to 8)
  - B. Qutput skew,  $t_{sk(0)}$ , from A to any Y (any phase), can be measured between outputs for which the respective polarity-control inputs  $(\overline{T}/C)$  are at the same or different logic levels. It is calculated as the greater of:
    - The difference between the fastest and slowest of tp<sub>LH</sub> from A<sup>↑</sup> to any Y or tp<sub>HL</sub> from A<sup>↑</sup> to any Y (e.g., tp<sub>LHn</sub>, n = 1 to 4; or tp<sub>LHn</sub>, n = 5 to 6, and tp<sub>HLn</sub>, n = 7 to 8)
    - The difference between the fastest and slowest of tp<sub>HL</sub> from A↓ to any Y or tp<sub>LH</sub> from A↓ to any Y (e.g., tp<sub>HLn</sub>, n = 1 to 4; or tp<sub>HLn</sub>, n = 5 to 6, and tp<sub>LHn</sub>, n = 7 to 8)

Figure 2. Waveforms for Calculation of t<sub>sk(o)</sub>





### PACKAGE OPTION ADDENDUM

16-Dec-2006

### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
CDC392D	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
CDC392DR	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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